Test Beam Results of 3D Detectors in CVD Diamond Harris Kagan Ohio State University for the RD42 Collaboration XXXIX Int'l Conference on High Energy Physics (ICHEP2018) Seoul, South Korea July 7, 2018

<u>Outline of Talk</u>

- Introduction Motivation, Properties and RD42
- 3D Device in pCVD Diamond
- Test Beam Results of CMS, ATLAS 3D Diamond Pixel Devices
- Summary



Distinct properties interesting for HEP applications:

- Large band gap
- High thermal conductivity \rightarrow no cooling required
- Large displacement energy \rightarrow high radiation tolerance
- Low dielectric constant, $I_L \rightarrow$ low capacitance, low noise

Disadvantages:

• Large band gap

 \rightarrow planar detectors give ~1/2 signal of Si (same t)

 \rightarrow no free carriers, low leakage current, I_I

At the HL-LHC the innermost detectors may see

• Extreme conditions

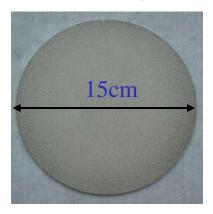
→ fluences up to 10^{16} - 10^{17} /cm² and → rates up to 200MHz-1GHz/cm²

At large radiation doses, w/o gain, the drift distance relative to the mean free path determines signal size

• Next talk (A. OH) \rightarrow mean free path



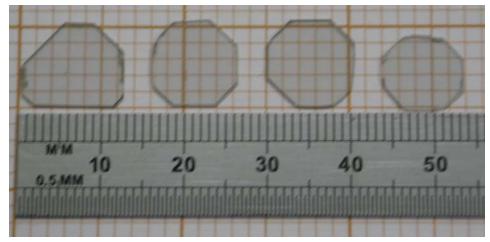
Polycrystalline CVD (pCVD) Wafer Growth



Wafers 14-15cm diameter; wafer collection distance 400µm-500µm

Uniformity across wafer ~5%

Single-crystal CVD (scCVD) Wafer Growth



Wafers 5-10mm × 5-10mm; scCVD diamond collects full charge

Uniformity better than 1%

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Introduction - The 2018 RD42 Collaboration



The 2018 RD42 Collaboration

A. Alexopoulos³, M. Artuso²⁰, F. Bachmair²⁴, L. Bäni²⁴, M. Bartosik³, J. Beacham¹³, H. Beck²³, V. Bellini², V. Belyaev¹², B. Bentele¹⁹, P. Bergonzo¹¹, A. Bes²⁷, J-M. Brom⁷, M. Bruzzi⁴, G. Chiodini²⁶, D. Chren¹⁸, V. Cindro⁹, G. Claus⁷, J. Collot²⁷, J. Cumalat¹⁹, A. Dabrowski³, R. D'Alessandro⁴, D. Dauvergne²⁷, W. de Boer¹⁰, S. Dick¹³ C. Dorfer²⁴, M. Dunser³, G. Eigen³⁰, V. Eremin⁶, J. Forneris¹⁵, L. Gallin-Martel²⁷, M.L. Gallin-Martel²⁷, K.K. Gan¹³, M. Gastal³, C. Giroletti¹⁷, M. Goffe⁷, J. Goldstein¹⁷, A. Golubev⁸, A. Gorišek⁹, E. Grigoriev⁸, J. Grosse-Knetter²³, A. Grummer²¹, M. Guthoff³, B. Hiti⁹, D. Hits²⁴, M. Hoeferkamp²¹, T. Hofmann³, J. Hosslet⁷, J-Y. Hostachy²⁷, F. Hügging¹, C. Hutton¹⁷, J. Janssen¹, H. Kagan¹³, K. Kanxheri²⁸, G. Kasieczka²⁴, R. Kass¹³, M. Kis⁵, G. Kramberger⁹, S. Kuleshov⁸, A. Lacoste²⁷, S. Lagomarsino⁴, A. Lo Giudice¹⁵, E. Lukosi²⁵, C. Maazouzi⁷, I. Mandic⁹, A. Marino¹⁹, C. Mathieu⁷, M. Menichelli²⁸, M. Mikuž⁹, A. Morozzi²⁸, J. Moss²⁹, R. Mountain²⁰, S. Murphy²², M. Muškinja⁹, A. Oh²², P. Olivero¹⁵, D. Passeri²⁸, H. Pernegger³, R. Perrino²⁶, F. Picollo¹⁵, M. Pomorski¹¹, R. Potenza², A. Quadt²³, F. Rarbi²⁷, A. Re¹⁵, M. Reichmann²⁴ G. Riley²⁵, S. Roe³, D. Sanz²⁴, M. Scaringella⁴, D. Schaefer³, C. Schmidt⁵, E. Schioppa³, S. Schnetzer¹⁴, S. Sciortino⁴, A. Scorzoni²⁸, S. Seidel²¹, L. Servoli²⁸, D.S. Smith¹³, B. Sopko¹⁸, V. Sopko¹⁸, S. Spagnolo²⁶, S. Spanier²⁵, K. Stenson¹⁹, R. Stone¹⁴, B. Stugu³⁰, C. Sutera², M. Traeger⁵, D. Tromson¹¹, W. Trischuk¹⁶, C. Tuve², J. Velthuis¹⁷, N. Venturi³, E. Vittone¹⁵, S. Wagner¹⁹, R. Wallny²⁴, J.C. Wang²⁰, J. Weingarten²³, C. Weiss³, N. Wermes¹, M. Yamouni²⁷, J. Zalieckas³⁰, M. Zavrtanik⁹

123 participants

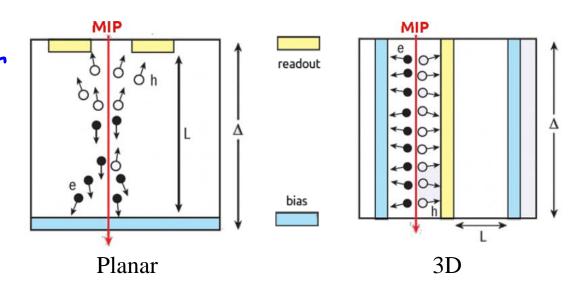
¹ Universität Bonn, Bonn, Germany ² INFN/University of Catania, Catania, Italy ³ CERN, Geneva, Switzerland ⁴ INFN/University of Florence, Florence, Italy ⁵ GSI. Darmstadt, Germany ⁶ loffe Institute, St. Petersburg, Russia ⁷ IPHC, Strasbourg, France ⁸ ITEP, Moscow, Russia ⁹ Jožef Stefan Institute, Ljubljana, Slovenia ¹⁰ Universität Karlsruhe, Karlsruhe, Germany ¹¹ CEA-LIST Technologies Avancees, Saclay, France ¹² MEPHI Institute, Moscow, Russia ¹³ The Ohio State University, Columbus, OH, USA ¹⁴ Rutgers University, Piscataway, NJ, USA ¹⁵ University of Torino, Torino, Italy ¹⁶ University of Toronto, Toronto, ON, Canada ¹⁷ University of Bristol, Bristol, UK ¹⁸ Czech Technical University, Prague, Czech Republic ¹⁹ University of Colorado, Boulder, CO, USA ²⁰ Syracuse University, Syracuse, NY, USA ²¹ University of New Mexico, Albuquerque, NM, USA ²² University of Manchester, Manchester, UK ²³ Universität Goettingen, Goettingen, Germany ²⁴ ETH Zürich, Zürich, Switzerland ²⁵ University of Tennessee, Knoxville, TN, USA ²⁶ INFN-Lecce, Lecce, Italy ²⁷ LPSC-Grenoble, Grenoble, Switzerland ²⁸ INFN-Perugia, Perugia, Italy ²⁹ California State University - Sacramento, CA, USA ³⁰ University of Bergen, Bergen, Norway

30 institutes

After large radiation fluence all detectors are trap limited •Mean free paths $\lambda < 50 \mu m$ •Need to keep drift distances (L) smaller than mfp (λ)

Comparison of planar and 3D devices

Can one do this in pCVD diamond?

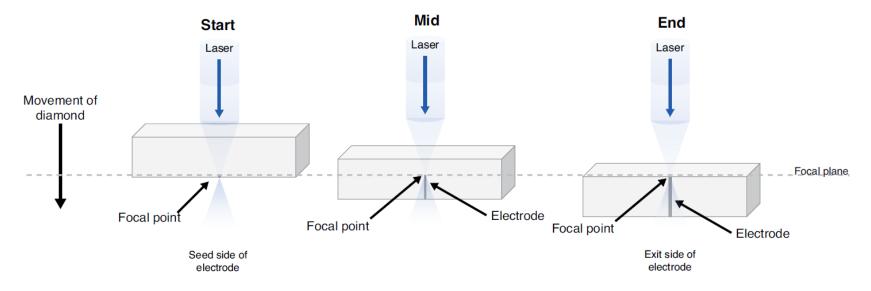


Have to make resistive columns in diamond for this to work -columns made with 800nm femtosecond laser -initial cells 150 μ m x 150 μ m; columns 6 μ m diameter



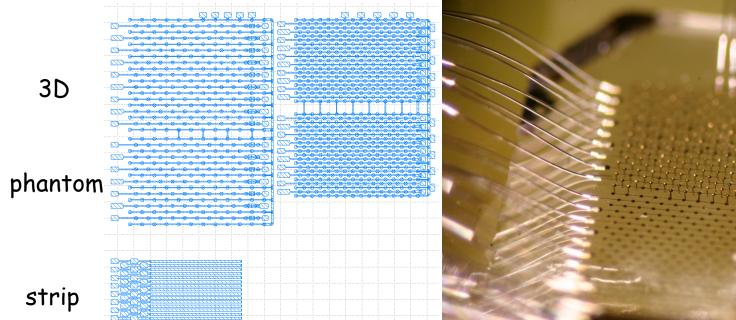
Femtosecond laser converts insulating diamond into resistive mixture of various carbon phases: amorphous carbon, DLC, nano-diamond, graphite.

- Initial methods had 90% column yield \rightarrow now >99% yield with Spatial Light Modulation (SLM)
- Initial column diameters 6-10 $\mu m \rightarrow$ now 2.6 μm



3D Device in pCVD Diamond

Simultaneously readout all 3 devices

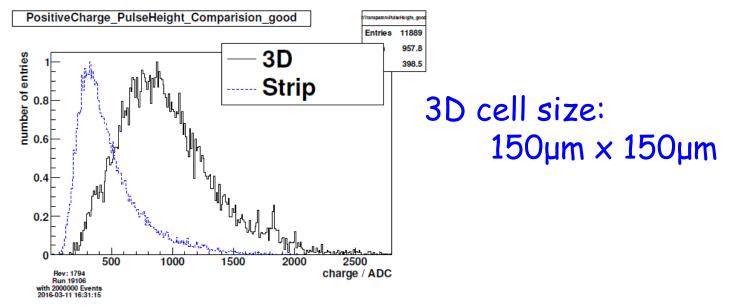


Two years ago we showed the results in scCVD diamond -Compared scCVD strip detector (500V) with 3D (25V) Last year the first 3D device in pCVD diamond -Compare pCVD strip detector (500V) with 3D (60V) This year the first 3D pixel detectors in pCVD diamond



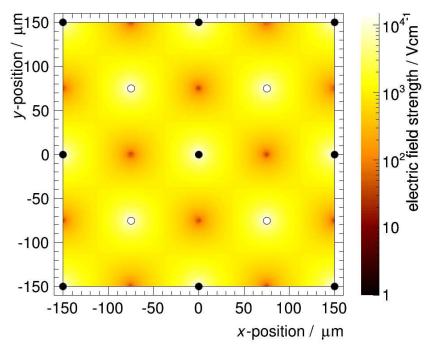
• Measured signal (diamond thickness 500µm):

- Planar Strip ave charge
 - 6,900e or ccd=192µm
- 3D ave charge
 - $13,500e \text{ or } ccd_{eq} = 350-375 \mu m$
- For the first time collect >75% of charge in pCVD





- Measurements consistent with TCAD simulations:
 - Large cells, large diameter columns → lower field regions in saddle points



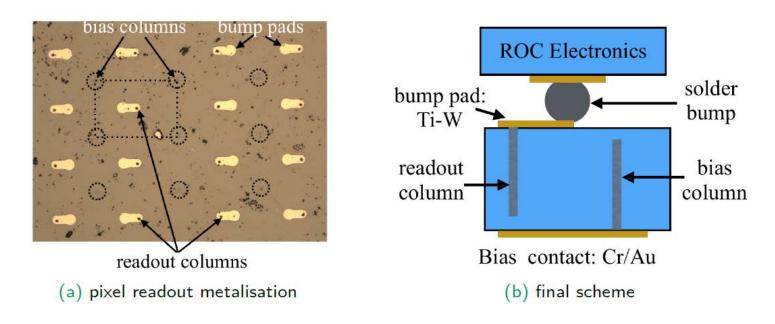
Cell size: 150µm x 150µm Voltage: 25V

Worked well enough to construct first pCVD 3D diamond pixel device

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First 3D pixel device in pCVD (2017) - [150µm x 100µm cells]

- Produced cells with 150µm x 100µm size for CMS pixel readout chip
- Cleaning, photolithography, metal contact to pixel and bias RD42
- Bump and wire bonding Princeton



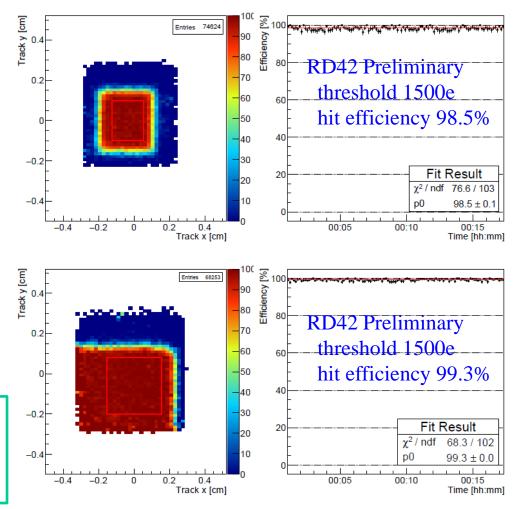
Results of CMS, ATLAS 3D pCVD Pixel Devices

3D Diamond Pixel 98.5% efficiency

- applied voltage: -55V
- pixel threshold: 1500e
- efficiencies flat in time

Planar Silicon Pixel (ref) 99.3% efficiency

 lower efficiency in diamond most likely due to low field regions

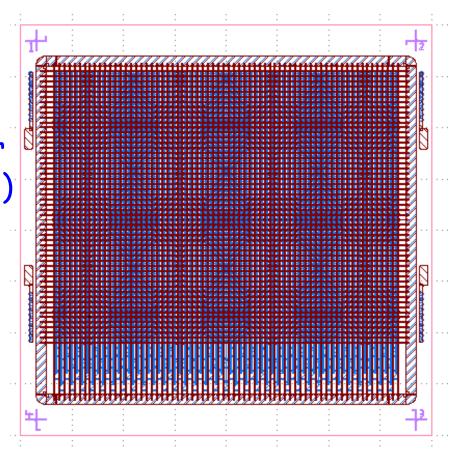


(a) efficiency maps

(b) hit efficiencies

Produced new 7200 cell pixel prototype w/50µm x 50µm pitch

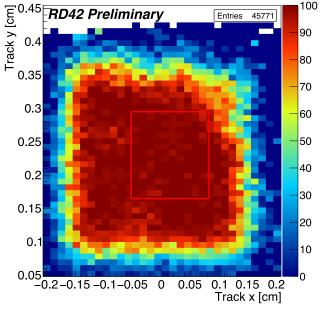
• Two fabricated: • Oxford complete • Manchester complete 50µm x 50µm cells ganged for CMS (3x2) and ATLAS (1x5) Metallization • CMS complete • ATLAS in progress • Bump bonding • CMS @Princeton complete • ATLAS @IFAE in progress • First one (CMS) tested in Aug 2017 Test Beam @PSI

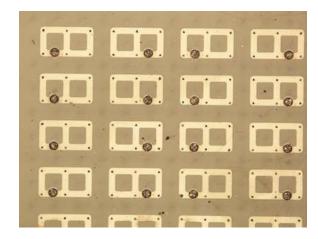


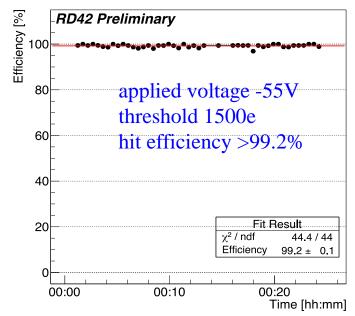
Results of CMS, ATLAS 3D pCVD Pixel Devices

Preliminary Results (50µm×50µm pixels)

- Readout with CMS pixel readout 6 columns (3x2) ganged together
- Preliminary efficiency >99.2%
- Collect >90% of charge!







Summary



Lots of progress in diamond with HL-LHC in view

3D detector prototypes made great progress

- 3D works in pCVD diamond
- Scale up (x70) worked
- Smaller cells (50µm × 50µm) worked
- Thinner columns (2.6µm) worked

3D diamond pixel devices being produced

- All work as expected
- Visible improvements with each step
- Efficiencies look good

Future plans

- Irradiate devices to 10¹⁷ this year
- Continue scale up (x10) and/or smaller cells (25µm x 25µm)



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